
**Migration from RevY to RevV for STM32H743/753
and STM32H750 Value line microcontrollers**

Introduction

The major limitations identified on silicon revision Y (RevY) of STM32H743/753xx and STM32H750 Value line MCUs have been fixed on revision V (RevV).

The detailed list of limitations is available in the errata sheet document. In addition to fixed limitations, some peripheral updates have been carried out.

This application note shows the differences to take in consideration when migrating from one revision to another.

For STM32H750 Value line MCUs all listed updates are available, unless those related to the Flash memory features, restricted to STM32H743/753xx.

RevV is software compatible with revision X (RevX), there is no functional difference between them.

Regarding electrical characteristics, there is no difference in between RevX and RevV, except for the USB pull-up enhancement.

RM0433 “STM32H743/753 and STM32H750 advanced ARM[®]-based 32-bit MCUs”, available on www.st.com, is the reference document.

Contents

- 1 Modified peripherals 5**
 - 1.1 FLASH 5
 - 1.1.1 Write sequence 5
 - 1.1.2 Dynamic swap bank 6
 - 1.1.3 Flash memory CRC 6
 - 1.2 PWR 7
 - 1.2.1 Voltage scaling 7
 - 1.2.2 Monitoring low-power modes 7
 - 1.3 RCC 8
 - 1.3.1 HSI / CSI trimming bits extension 8
 - 1.3.2 Kernel clocks 8
 - 1.3.3 LSE drive change on the fly 8
 - 1.4 CRS 9
 - 1.5 GPIO 9
 - 1.6 SYSCFG 9
 - 1.6.1 Boost VDD selection 9
 - 1.7 ADC 10
 - 1.7.1 ADC clocks 10
 - 1.7.2 ADC boost 10
 - 1.7.3 ADC resolution 10
 - 1.8 CRYP 11
 - 1.9 USB 11
 - 1.10 TIM 13

- 2 Conclusion 14**

- 3 Revision history 15**

List of tables

Table 1.	VOS0 overview	7
Table 2.	Low-power modes monitoring pin overview	7
Table 3.	GPIO state according to CPU and domain state	7
Table 4.	External pin selection	9
Table 5.	New alternate functions	9
Table 6.	ADC clock frequency	10
Table 7.	ADC resolution	11
Table 8.	Updated OTG_HS registers	12
Table 9.	Alternate functions	13
Table 10.	Document revision history	15

List of figures

Figure 1.	Change in FLASH_OPTCR register	6
Figure 2.	Changes in FLASH registers	6
Figure 3.	Changes in RCC registers	8
Figure 4.	ADC block diagram	10
Figure 5.	Changes in CRYP_CR register	11

1 Modified peripherals

The STM32H7 Series microcontrollers are based on Arm^{®(a)} Cortex[®] processor(s).

The following peripherals have been modified passing from RevY to RevV:

- *FLASH*
- *PWR*
- *RCC*
- *CRS*
- *GPIO* (alternate functions only)
- *SYSCFG*
- *ADC*
- *CRYP*
- *USB*
- *TIM*

1.1 FLASH

1.1.1 Write sequence

On RevV the behavior of BSY1/2 has changed compared to RevY. This bit indicates that an effective write, erase or option byte change operation is ongoing in the non-volatile memory. The bit can toggle during the write operation.

The recommended write sequence is updated as follows:

1. unlock the FLASH_CR1/2 register (only if register is not already unlocked)
2. enable write operations by setting the PG1/2 bits in the FLASH_CR1/2 registers
3. check the protection of the targeted memory areas
4. write one Flash memory word (corresponding to 32-byte) data starting at a 32-byte aligned address
5. check that QW1/QW2 (respectively for FLASH_CR1/2) has been set high and wait until it is reset to 0.

This change has an impact on custom Flash memory loader/write sequence.

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1.2 PWR

1.2.1 Voltage scaling

In addition to voltage scales available on RevY, RevV introduces a new V_{core} level (VOS0) that boosts the device performance (maximum frequency). VOS0 is activated via a dedicated sequence and a bit in the SYSCFG controller.

Table 1. VOS0 overview

VOS0	RevY	RevV
Typical range	Not available	1.36 V
Flash memory wait states		4

1.2.2 Monitoring low-power modes

RevV introduces low-power state monitoring pins, to monitor the CPU and domain state transition to low-power modes. The GPIO pin corresponding to each monitoring signal has to be programmed in alternate function mode.

This feature is not available in system Standby mode since these I/O pins are switched to high impedance.

Table 2. Low-power modes monitoring pin overview

Power state monitoring pins	Description
CSLEEP	Sleeping state
CDSLEEP	Deep sleep CPU state
DxPWREN	Domain (Dx, x= 1 or 2) power enabled

The values of the monitoring pins reflect the state of the CPU(s) and domain(s). Refer to [Table 3](#) for the GPIO state depending on CPU and domain state.

Table 3. GPIO state according to CPU and domain state

Domain DxPWREN	CPU		Power state	
	CSLEEP	CDSLEEP	CPU	Domain x
1	0	0	Run mode	DRun mode
1	1	0	Sleep mode	
1	0	1	Run mode	
1	1	1	Deep sleep mode	DStop mode
0	-	-	-	DStandby mode

1.3 RCC

1.3.1 HSI / CSI trimming bits extension

Register RCC_ICSCR in RevY is replaced in RevV by the two registers RCC_HSICFGR and RCC_CSICFGR. As shown in [Figure 3](#):

- HSITRIM and HSICAL (cells in gray) are moved to RCC_HSICFGR register and HSITRIM bit field is extended from 6 to 7 bits
- CSITRIM and CSICAL (cells in light gray) are moved to the RCC_CSICFGR register, CSITRIM bit field is extended from 5 to 6 bits and CSICAL bit field is extended from 8 to 10 bits.

The bit field offsets are changed compared to RevY.

Figure 3. Changes in RCC registers

Rev Y																																
0x004	RCC_ICSCR	Res.	CSITRIM[4:0]				CSICAL[7:0]				HSITRIM[5:0]				HSICAL[11:0]																	
	Reset value		1	0	0	0	0	-	-	-	-	-	-	-	-	1	0	0	0	0	0	-	-	-	-	-	-	-	-	-	-	-
RevV																																
0x004	RCC_HSICFGR	Res.	HSITRIM[6:0]							Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	HSICAL[11:0]											
	Reset value		1	0	0	0	0	0	0													X	X	X	X	X	X	X	X	X	X	X
0x00C	RCC_CSICFGR	Res.	Res.	CSITRIM[5:0]				Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	CSICAL[9:0]											
	Reset value			1	0	0	0	0	0												X	X	X	X	X	X	X	X	X	X	X	

1.3.2 Kernel clocks

On RevV the ADC requires an input clock two times faster than the sampling clock. The maximum allowed ADC input clock frequency is 100 MHz instead of 36 MHz.

1.3.3 LSE drive change on the fly

The LSE also offers a programmable driving capability (LSEDRV[1:0]) that can be used to modulate the amplifier driving capability. On RevV the driving capability cannot be changed when the LSE oscillator is ON.

1.4 CRS

To allow the user application to tune HSI48 oscillator using an external source, the SYNC signal source in RevV authorizes to select an external pin (via the SYNC SRC bit field of the CRS_CFGR register).

Table 4. External pin selection

SYNCSRC	RevV	RevY
0	CRS_SYNC pin (external) is the SYNC signal	OTG HS2 SOF is the SYNC signal
1	LSE is the SYNC signal	
2	OTG HS1 SOF is the SYNC signal	
3	OTG HS2 SOF is the SYNC signal	Reserved

Binary codes using OTG HS2 SOF as SYNC signal on RevY are not compatible with RevV.

1.5 GPIO

For more flexibility, new alternate functions are added on RevV.

Table 5. New alternate functions

Number	Name
PB3: AF10	CRS_SYNC
PG11: AF01	LPTIM1_IN2
PC2: AF0	CDSLEEP
PC3: AF0	CSLEEP
PA4: AF0	D1PWREN
PA5: AF0	D2PWREN

There is no impact on applications designed with RevY.

1.6 SYSCFG

1.6.1 Boost V_{DD} selection

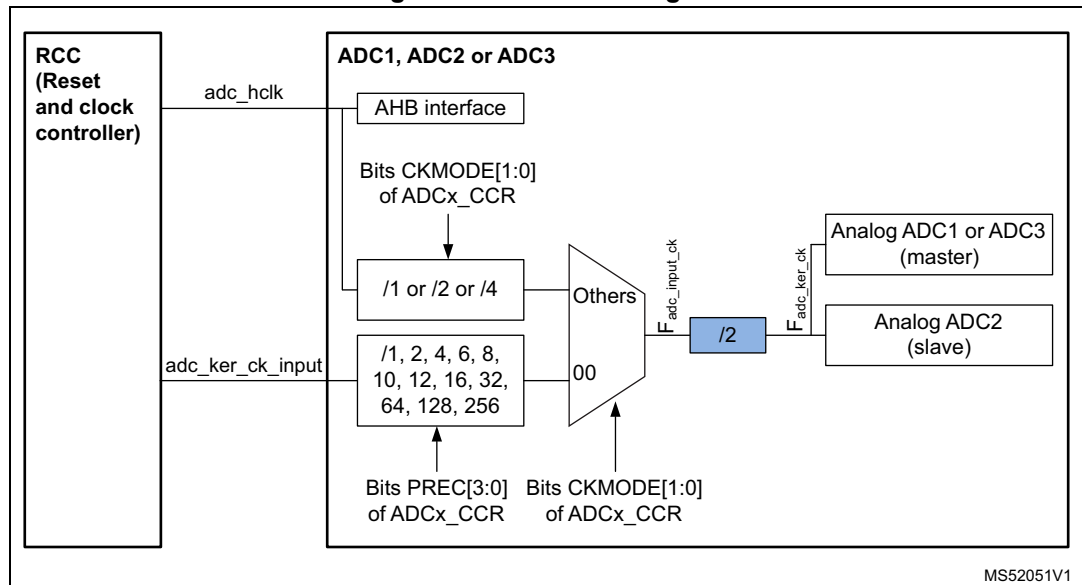
BOOSTVDDSEL bit is added to the SYSCFG_PMCR register to select the analog switch supply voltage.

1.7 ADC

1.7.1 ADC clocks

One of the major changes on the ADC interface is the clock scheme. With the addition of a divider by 2 (highlighted in [Figure 4](#)) F_{adc_ker_ck} for analog block is half the ADC input clock frequency.

Figure 4. ADC block diagram



On RevV the ADC kernel clock must be twice the frequency needed for the sampling (as an example, if a 25 MHz clock is needed, ADC kernel clock must be set to 50 MHz).

1.7.2 ADC boost

On RevV Boost mode control bit of ADC_CR register is modified, the BOOST configuration bit is extended from a single bit to two bits. The possible configurations are defined in [Table 6](#).

Table 6. ADC clock frequency

BOOST[9:8]	RevV	RevY
00	$f \leq 6.25 \text{ MHz}$	$f < 20 \text{ MHz}$
01	$6.25 \text{ MHz} < f \leq 12.5 \text{ MHz}$	$f > 20 \text{ MHz}$
10	$12.5 \text{ MHz} < f \leq 25 \text{ MHz}$	Not available
11	$25 \text{ MHz} < f \leq 50 \text{ MHz}$	

1.7.3 ADC resolution

On RevV the data resolution bitfield (bits 4:2 RES[2:0] bits of ADC_CFGR register) is modified as shown in [Table 7](#).

Table 7. ADC resolution

RES[2:0]	RevV	RevY
000	16-bit	
001	14-bit	
010	12-bit	
011	10-bit	
100	Reserved	8-bit
111	8-bit	Reserved

1.8 CRYPT

RevV supports hardware management for GCM encryption or CCM decryption with the last block of payload size inferior to 128 bits. This is possible thanks to the addition of the NPBLB bit field (the highlighted cells in *Figure 5*) in the CRYPT_CR register.

Figure 5. Changes in CRYPT_CR register

RevY															
31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	ALGO MODE3	Res.	GCM_CCMPH [1:0]	
												rw		rw	rw
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
CRYPTEN	FFLUSH	Res.	Res.	Res.	Res.	KEYSIZE[1:0]		DATATYPE[1:0]		ALGOMODE[2:0]		ALGODIR	Res.	Res.	
rw	w					rw	rw	rw	rw	rw	rw	rw	rw		
RevV															
31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	NPBLB[3:0]				ALGO MODE3	Res.	GCM_CCMPH [1:0]	
								rw	rw	rw	rw	rw		rw	rw
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
CRYPTEN	FFLUSH	Res.	Res.	Res.	Res.	KEYSIZE[1:0]		DATATYPE[1:0]		ALGOMODE[2:0]		ALGODIR	Res.	Res.	
rw	w					rw	rw	rw	rw	rw	rw	rw	rw		

1.9 USB

The USB controller on RevV is updated to support descriptor-based scatter / gather DMA controller for Device and Host mode, improving performance for Device mode isochronous endpoints. Software needs to be modified to support scatter / gather feature.

Table 8. Updated OTG_HS registers

Register	RevV	RevY	Comments
OTG_HCFG	<ul style="list-style-type: none"> – Bit 26 PERSSCHEDENA: Enable periodic scheduling – Bits 25:24 FRLSTEN[1:0]: Frame list entries – Bit 23 DESCDMA: Enable scatter / gather DMA mode 	– Bit [26:23] Reserved	Applicable in host scatter / gather DMA mode only
OTG_HFLBADDR	– HFLBADDR[31:0]: The starting address of the frame list (scatter/gather mode).	-	
OTG_HCCHARx	– Bit 29: Reserved	– Bit 29: ODDFRM: Odd frame	ODDFRM bit reserved in RevV
OTG_HCINTx	<ul style="list-style-type: none"> – Bit 13 DESCLSTROLL: Descriptor rollover interrupt. – Bit 12 XCSXACTERR: Excessive transaction error. – Bit 11 BNA: Buffer not available interrupt. 	– Bit [13:11]: Reserved	Applicable in host scatter / gather DMA mode only
OTG_HCINTMSKx	<ul style="list-style-type: none"> – Bit 13 DESCLSTROLLMSK: Descriptor rollover interrupt mask register. – Bit 11 BNAMSK: Buffer not available interrupt mask register. – Bit 2 AHBERRM: AHB error. In scatter/gather DMA mode for host, interrupts will not be generated due to the corresponding bits set in OTG_HCINTx. 	– Bit 2: AHBERRM: AHB error	
OTG_HSIZEGx	New register	-	Applicable in host scatter / gather DMA mode only
OTG_HCDMASGx		-	
OTG_HCDMABx		-	
OTG_DIEPMSK	– Bit 9: BNAM: BNA interrupt mask	-	Applicable in Device mode
OTG_DOEPMSK		-	
OTG_HS_DIEPEACHMSK1		-	
OTG_HS_DOEPEACHMSK1		-	
OTG_DIEPINTx	– Bit 9 BNA: Buffer not available interrupt	-	
OTG_DOEPINTx		-	

1.10 TIM

The spdifrx_frame_sync is no longer mapped on TIM 17, but is linked to TIM12 on RevV.

Table 9. Alternate functions

Domain	Bus	Peripheral	Signal	RevY	RevV	Trigger input
D2	APB1	SPDIFRX	spdifrx_frame_sync	TIM17	TIM12	TI1_1

2 Conclusion

Although there is a large compatibility between RevV and RevY, migrating from one silicon revision to another requires a few adjustments, detailed in this document. For more details refer to RM0433, available on www.st.com.

3 Revision history

Table 10. Document revision history

Date	Revision	Changes
04-Apr-2019	1	Initial release.

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